



SOT2124-1

HVQFN88, thermal enhanced very thin quad flat package, no leads, 88 terminals, 0.4 mm pitch, 10 mm x 10 mm x 0.85 mm body

17 September 2020

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN88
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	08-07-2020
Manufacturer package code	98ASA01672D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	9.9	10	10.1	mm
package width	9.9	10	10.1	mm
package height	0.8	0.85	0.9	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	88	-	



HVQFN88, thermal enhanced very thin quad flat package, no leads, 88 terminals, 0.4 mm pitch, 10 mm x 10 mm x 0.85 mm body

2 Package outline

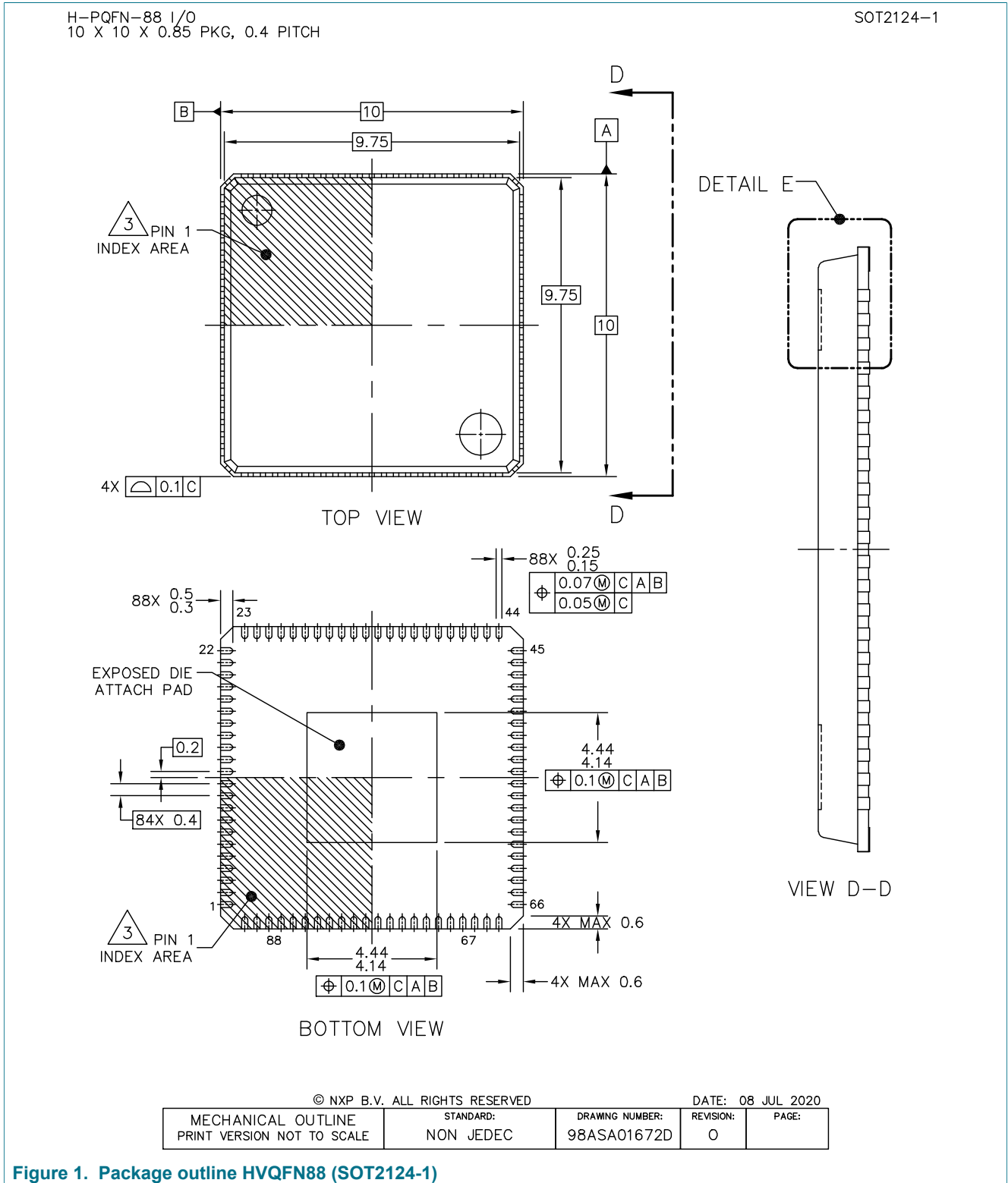
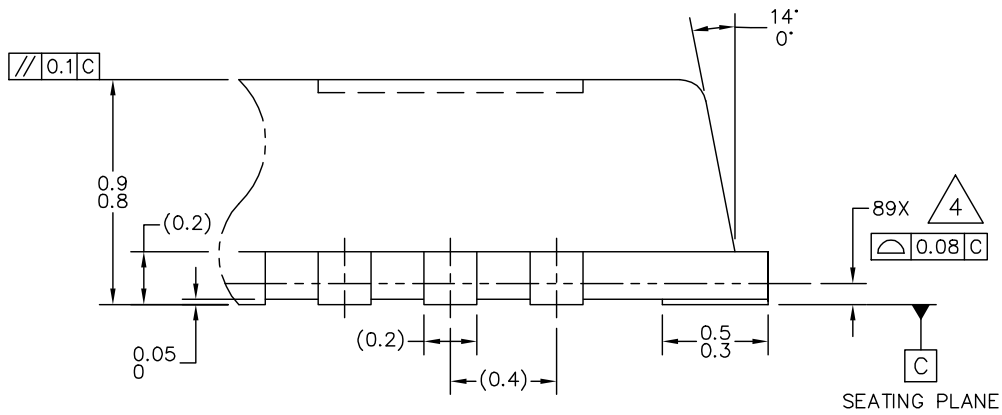


Figure 1. Package outline HVQFN88 (SOT2124-1)

HVQFN88, thermal enhanced very thin quad flat package, no leads, 88 terminals, 0.4 mm pitch, 10 mm x 10 mm x 0.85 mm body

H-PQFN-88 I/O
10 X 10 X 0.85 PKG, 0.4 PITCH

SOT2124-1



DETAIL E
VIEW ROTATED 90° CW

© NXP B.V. ALL RIGHTS RESERVED

DATE: 08 JUL 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01672D	REVISION: 0	PAGE:
--	------------------------	--------------------------------	----------------	-------

Figure 2. Package outline detail of HVQFN88 (SOT2124-1)

3 Soldering

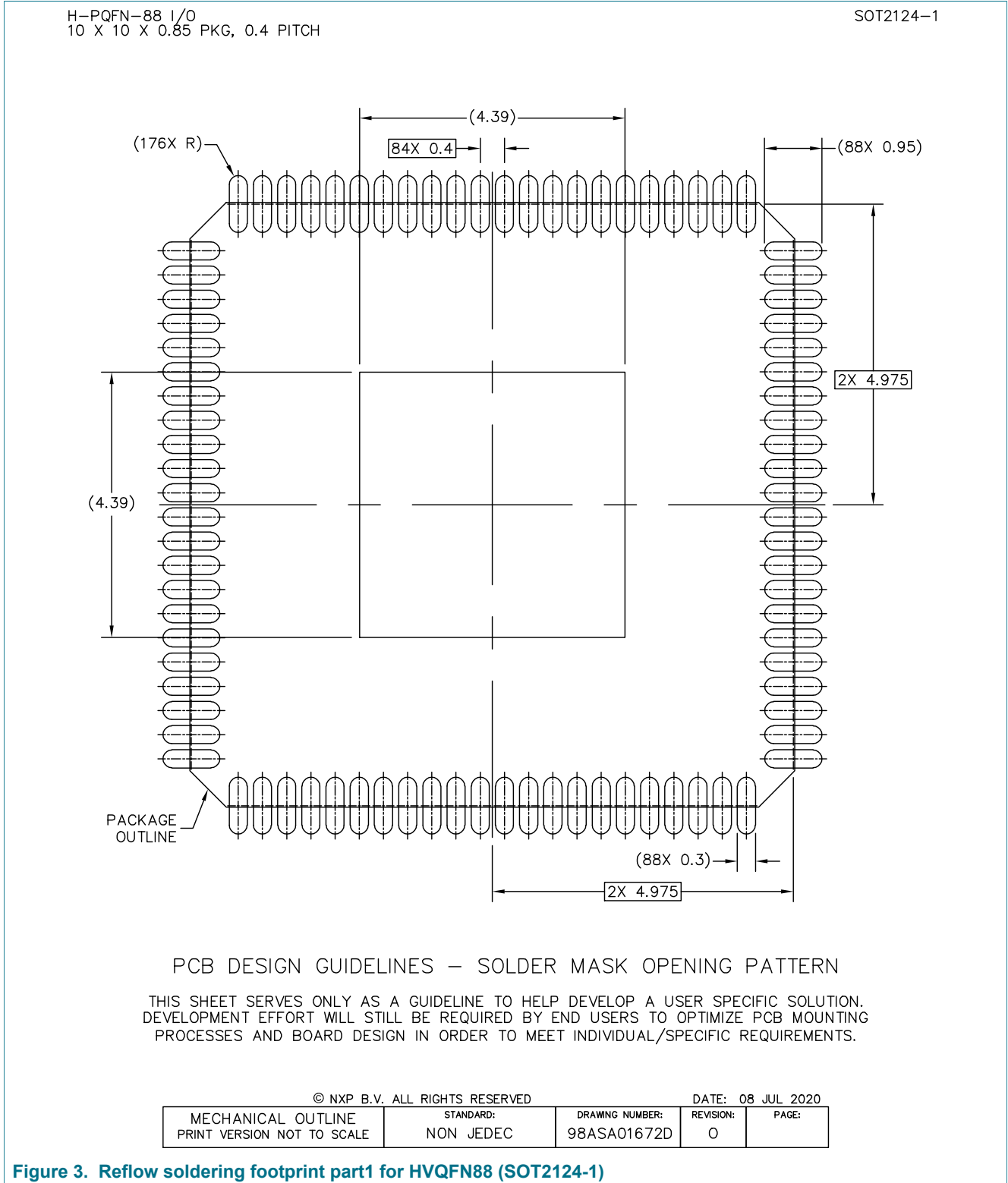
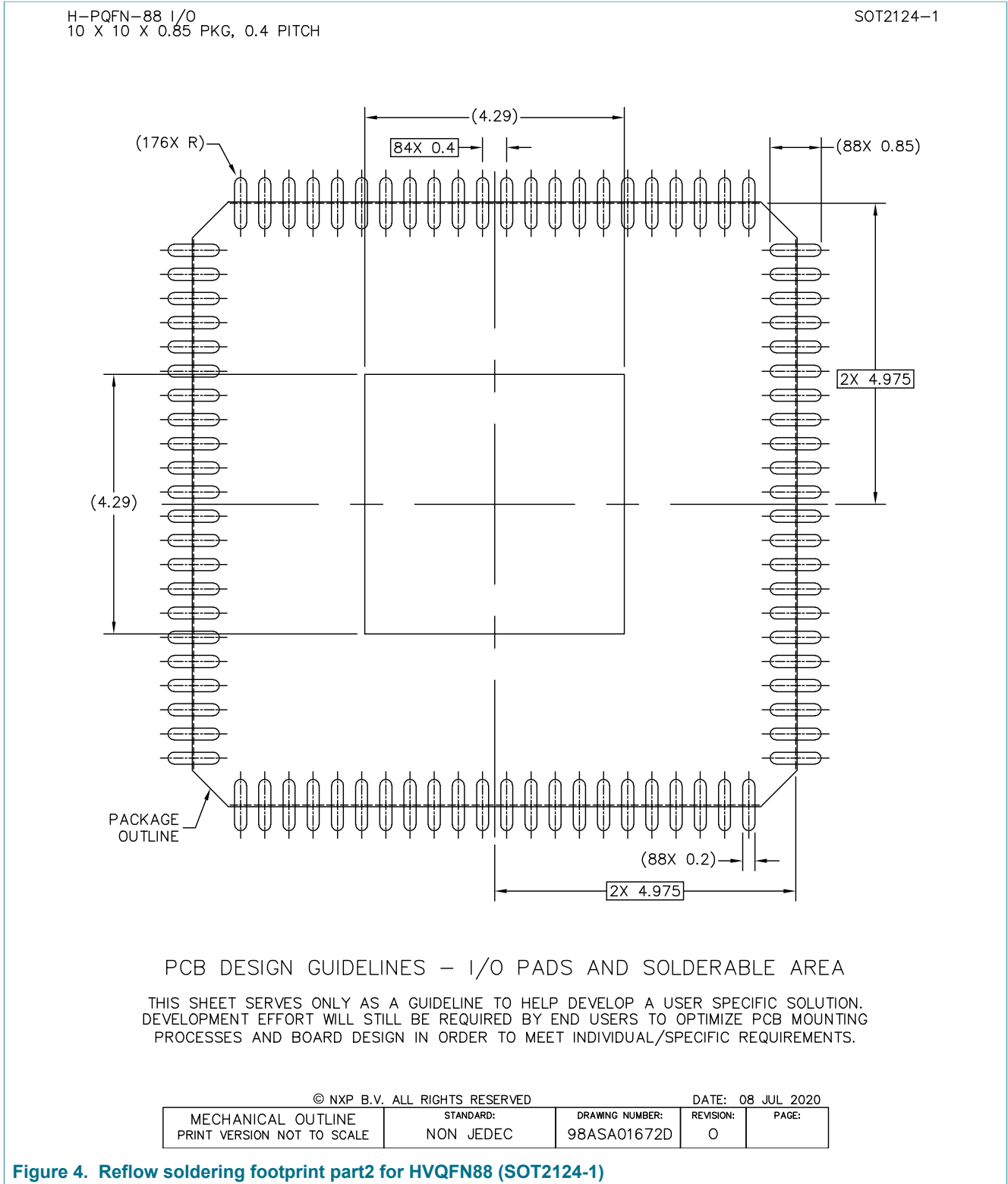


Figure 3. Reflow soldering footprint part1 for HVQFN88 (SOT2124-1)

HVQFN88, thermal enhanced very thin quad flat package, no leads, 88 terminals, 0.4 mm pitch, 10 mm x 10 mm x 0.85 mm body



HVQFN88, thermal enhanced very thin quad flat package, no leads, 88 terminals, 0.4 mm pitch, 10 mm x 10 mm x 0.85 mm body

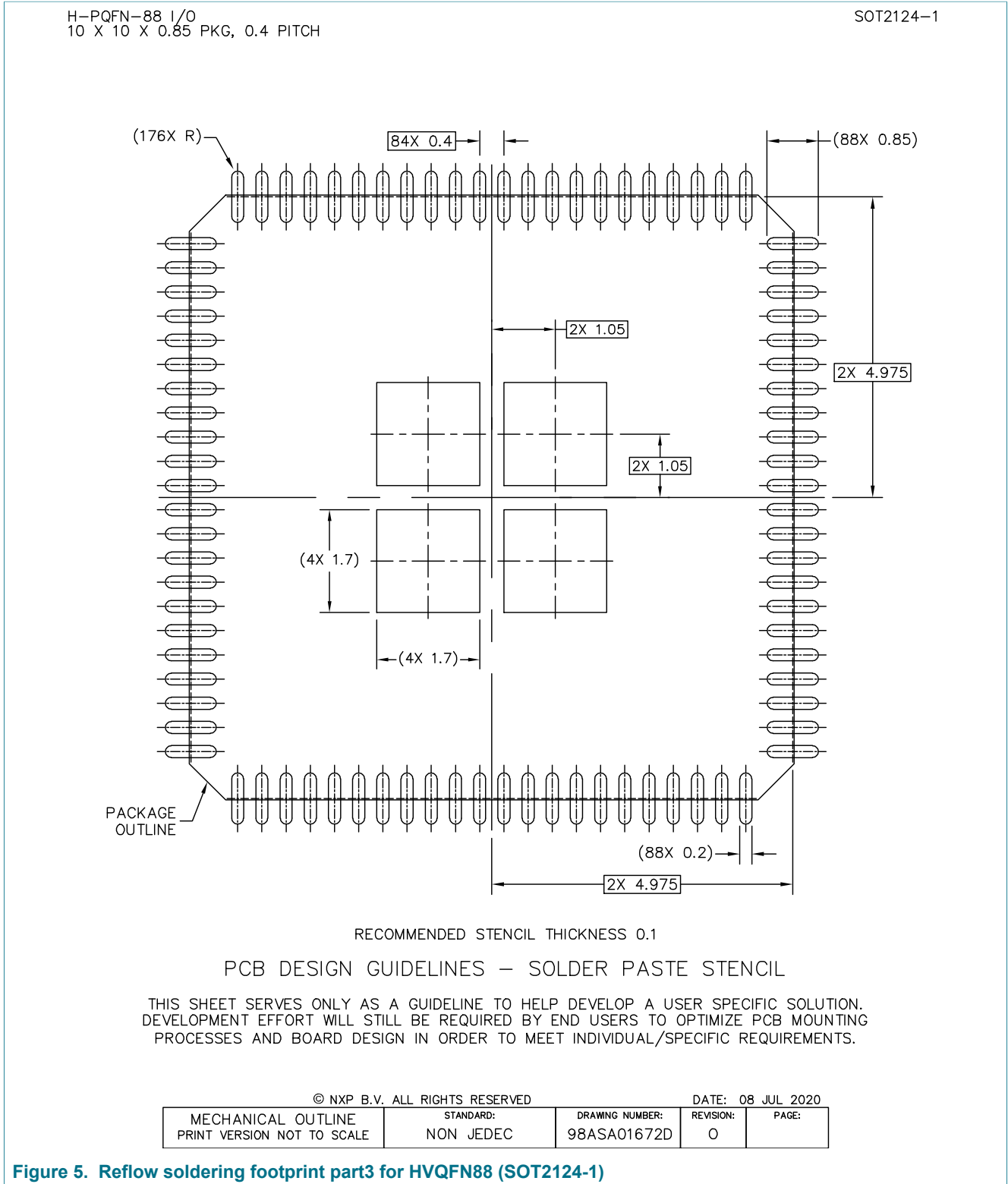


Figure 5. Reflow soldering footprint part3 for HVQFN88 (SOT2124-1)

HVQFN88, thermal enhanced very thin quad flat package, no leads, 88 terminals, 0.4 mm pitch, 10 mm x 10 mm x 0.85 mm body

H-PQFN-88 I/O
10 X 10 X 0.85 PKG, 0.4 PITCH

SOT2124-1

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

© NXP B.V. ALL RIGHTS RESERVED		DATE: 08 JUL 2020		
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01672D	REVISION: 0	PAGE:

Figure 6. Package outline note HVQFN88 (SOT2124-1)

4 Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Contents

1 Package summary1
2 Package outline2
3 Soldering4
4 Legal information8